



5600C

Automatic Bond Tester

The automatic bond tester 5600CS complements F&S BONDTEC Semiconductor GmbH die- and wire- bonders.

The PC controlled moving table allows any number of bonds to be tested automatically from a stored program.

Results can be analysed and output immediately or exported in a number of data base formats for subsequent analysis as desired.

Powerful extended capabilities enable measurements such as force/time or force/distance curves to be made and deliver more data about the quality of the bond tested.

Exchangeable measurement cartridges ensure rapid conversion to different force ranges. The calibration curves of all measurement cartridges are stored internally; additional heads for shear, peel and tweezer testing with customer-specific tools and jaws are available.

After a first programming a reproducible pull- or sheartest can be guaranteed for all following components.

Specifications

Mechanics

Table travel X, Y, Z

Work area: x= 100 mm y=115 mm optional
Resolution 0, 25 µm, repeatability < 2 µm

Speed

All axes programmable from 0.2 to 6 mm/s
Test speed from 0.2 to 5mm/s

Measurement heads

Accuracy

0.25 % of max value

Calibration

Stored in measurement head; temperature-compensated load cell
Optional calibration at customers side (specific tools)

Control

Computer

Single-Board PC, 1,6 GHz Dual Core processor,
4 GB RAM, Ethernet, USB 4x frontside

Monitor

TFT flat screen monitor Min. 17"

Operating system

Windows 7

Printer

all Windows-compatible printers can be installed

Additional features

Programming

Automatic repeat measurements on hybrids or COB using the programmable table movement and Pattern Recognition Unit (PRU)

Evaluation

Statistics such as mean value, standard deviation, trend, cp, cpk, etc. Based on SQL Databank

Export format

SQL, CSV, HTML

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Other Operator profile, various password levels, optional barcode readers for product identification; feedback of measured values to die and wire bonders for parameter optimisation optional

P2B option Communication with F&S BONDTEC die- or wire-bonder

Test-Cartridge

Pulltester Cartridge



Available Pullheads:

PH100C	100 cN
PH1000C	1000 cN
PH5000C	5000 cN

Sheartester Cartridge



Available Shearheads:

SH500C	500 cN
SH5000C	5000 cN

Tweezertester Cartridge



Available Tweezerhead

TH100C	100 cN
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The Test-Cartridges can be changed without any tool within less than 1 minute

General

Microscope Stereoskop Standard 40x, other Microscopes optional

Lighting 20 W halogen spot light (optionally LED ring light)

Dimensions Height 70 cm, width 70 cm, depth 65 cm; weight approx. 80 kg

Supplies 100...240 VAC, single phase, 50/60 Hz, max. 500VA

Connections Air 6 bar; vacuum 0, 7 bar

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